TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSIII)

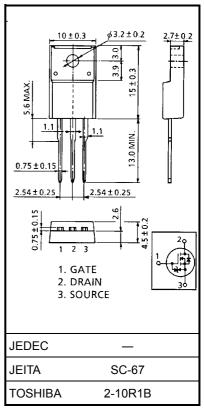
2SK2717

DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance $RDS(ON) = 2.3 \Omega$ (typ.)
- High forward transfer admittance $|Y_{fs}| = 4.4 \text{ S (typ.)}$
- Low leakage current $: IDSS = 100 \ \mu A \ (max) \ (VDS = 720 \ V)$
- Enhancement-mode : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	900	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	5	А	
	Pulse (Note 1)	I _{DP}	15	A	
Drain power dissipation	n (Tc = 25°C)	PD	45	W	
Single pulse avalanche energy (Note 2)		E _{AS}	595	mJ	
Avalanche current		I _{AR}	5	А	
Repetitive avalanche e	energy (Note 3)	E _{AR}	4.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	2.78	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 43.6 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution. Unit: mm

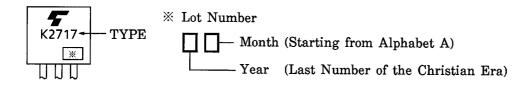
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V_{GS} = ±30 V, V_{DS} = 0 V	_		±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I_{G} = ±10 µA, V_{DS} = 0 V	±30	_		V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	-	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0		4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3.0 A		2.3	2.5	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 3.0 A	1.1	4.4	_	S
Input capacitance	e	C _{iss}			1200	_	pF
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		20	_	
Output capacitance		Coss			120	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{_{0V}} \prod_{\substack{ID = 3A \\ \downarrow \downarrow \downarrow \downarrow}} \circ V_{out}$ R_L $= 66.7\Omega$ $V_{DD} = 200V$	_	40	_	- ns
	Turn-on time	t _{on}		_	90	_	
	Fall time	t _f		_	60	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs	_	200	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	45	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 5 A		25	_	nC
Gate-drain ("miller") Charge		Q _{gd}			20	_	

Source–Drain Ratings and Characteristics (Ta = 25°C)

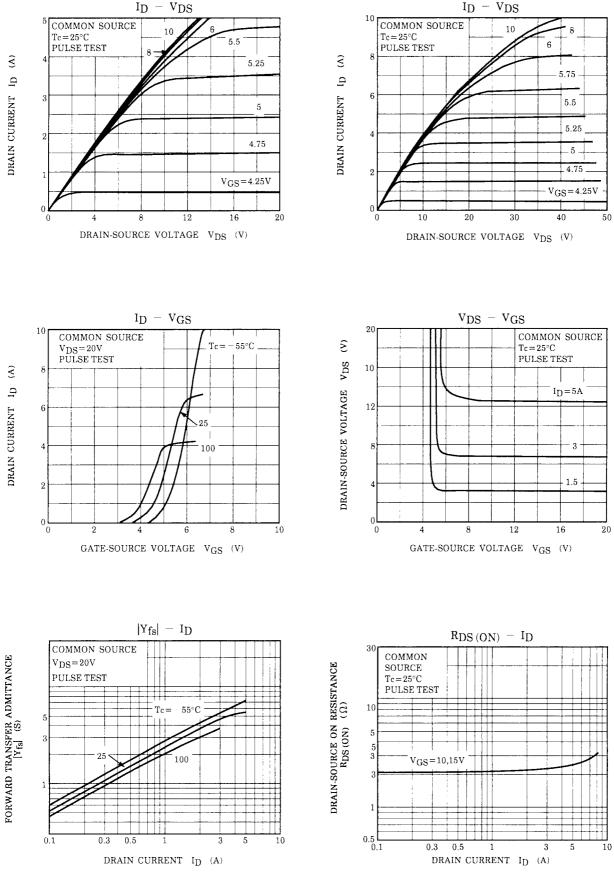
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	15	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		1300		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	11	_	μC

Marking

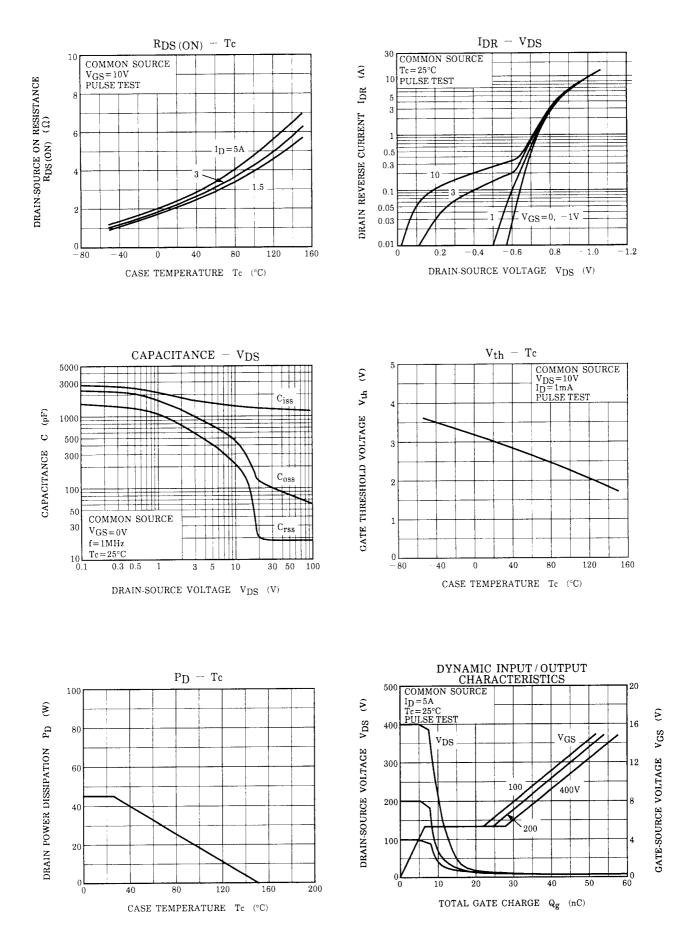


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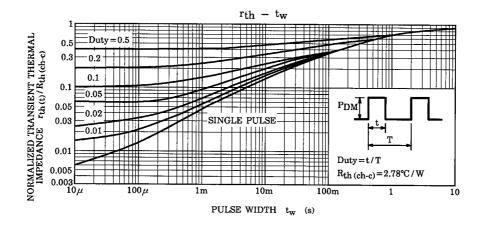
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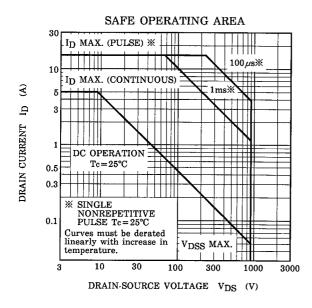


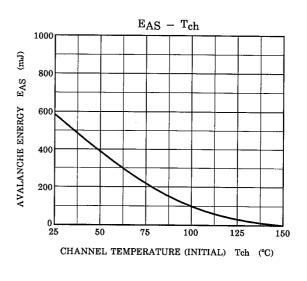
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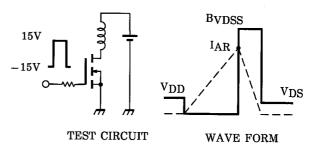


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